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## (54) ELECTRONIC COMPONENT AND METHOD FOR MANUFACTURING ELECTRONIC

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**COMPONENT** 

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#### (57)ABSTRACT

An electric component includes a printed circuit board with each of a pair of surfaces serving as a component mounting surface. The component mounting surface has a predetermined region on which electronic components are coated with a resin. A predetermined one of the electronic components in the region is not covered with the resin at a portion above a predetermined height from the component mounting surface.

